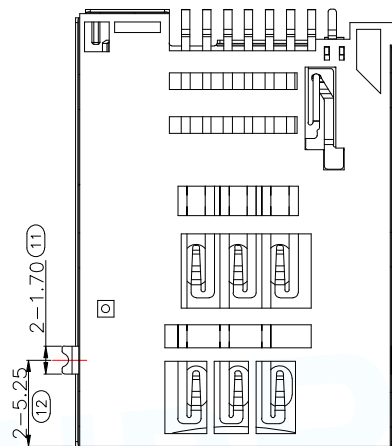
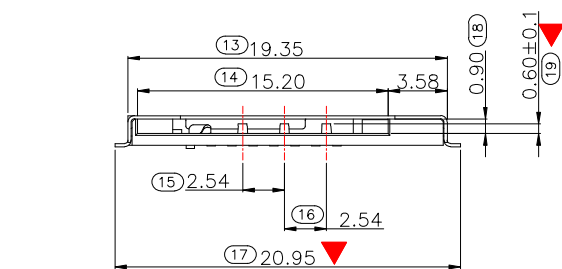


SIM示意图  
芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL



NOTES:

MATERIAL:

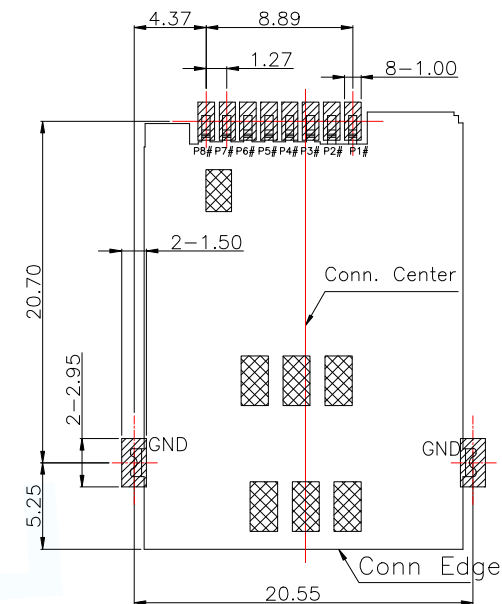
Insulator: High Temperature Thermoplastic, UL 94V-0.  
Contact: Copper Alloy  
CD PIN: Copper Alloy  
Shell: STAINLESS

PLATING:

Contact: Plated Ni , contact point gold plated G/F, welding feet Matte tin  
Shell: Plated Ni Overall Plated G/F Selective Contact Area  
CD PIN: Plated Ni, tin feet, contact point brush gold

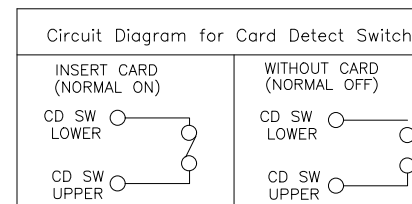
Electrical:

Current Rating :0.5A AC/DC max.  
Voltage Rating :30V AC/DC  
Ambient Temperature Range :-20°C~+60°C  
Storage Temperature Range :-40°C~+85°C  
Ambient Humidity Range :95% R.H. Max.  
Contact Resistance:100mΩ max.  
Insulation Resistance:1000MΩ min./500VDC  
Mating Cycles:5,000 Insertions  
Temperature:260°C ±5°

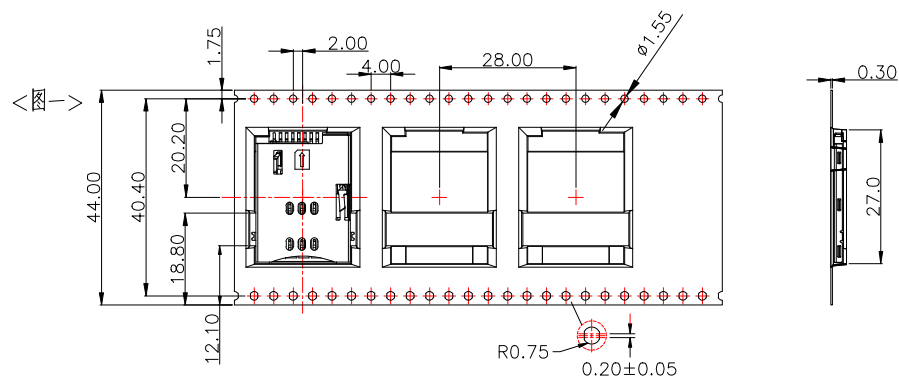


RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES:±0.05

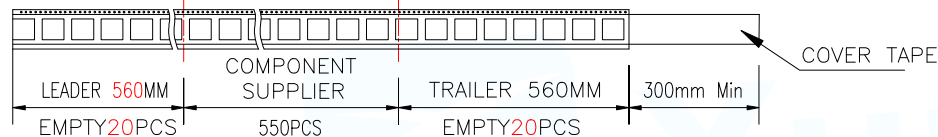
SOLDER AREA  
 NONE CIRCUIT DIAGRAM AREA



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: SIM PUSH H1.8(铁壳脚间距5.25)客户图	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	SIM-131-ARP8
DECIMALS:	ANGLES:	DWN		
.X:±0.30	X.':±2'	CHKD		
.XX:±0.20	X.X':±1'	APVD		
.XXX:±0.10		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
	Website address		REV:A	

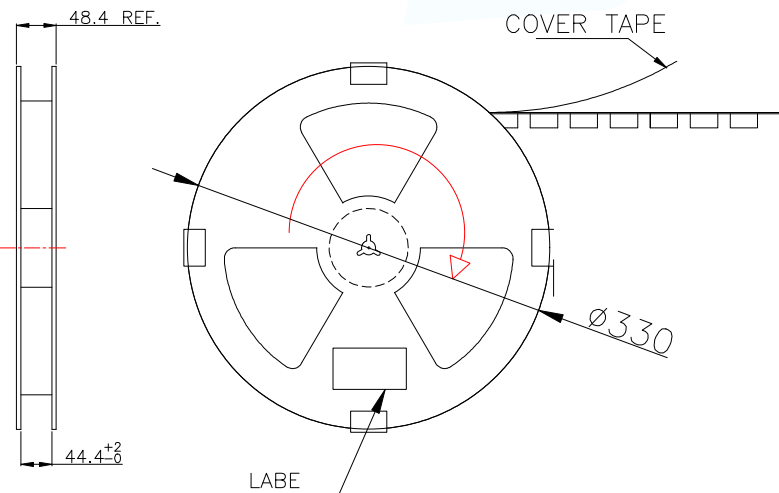


生产收料方向      客户出料方向



COVER TAPE PEELING FORCE:20gf~120gf

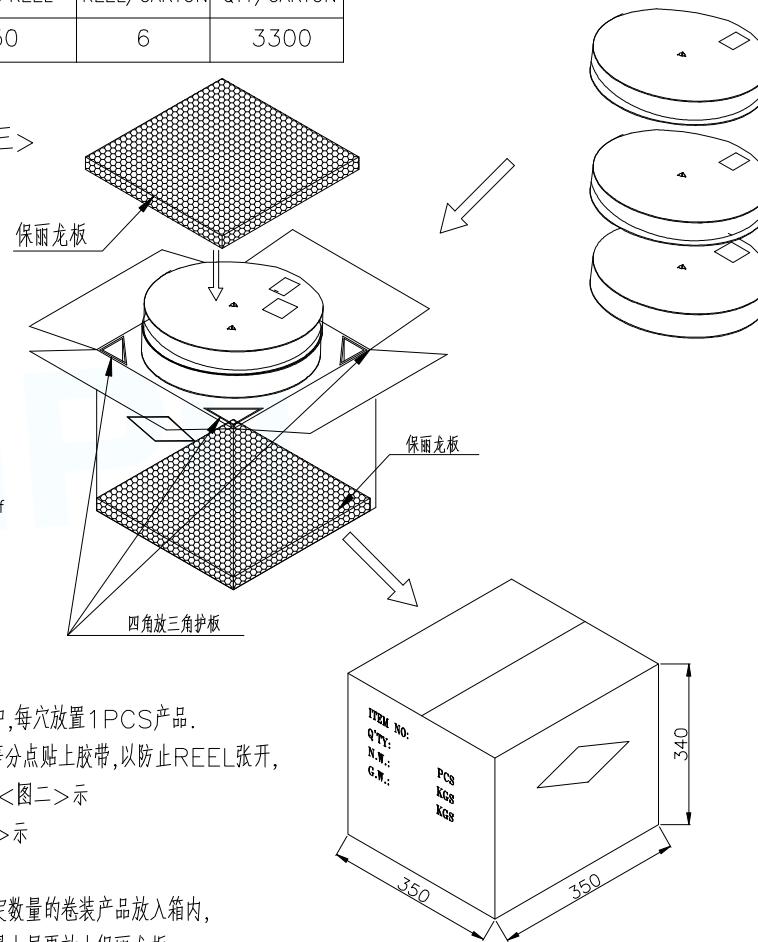
<图二>



<TABLE 1> PACKAGING QUANTITY

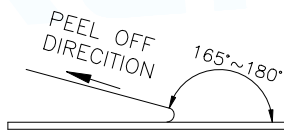
QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

<图三>



NOTE:

1. 依<图一>示放置产品于下载中,每穴放置1PCS产品.
2. 包装机包好后,在REEL的个等分点贴上胶带,以防止REEL张开,每REEL贴1PCS标签,如<图二>示
3. 包装数量见如<TABLE 1>示
4. 包装成箱见如<图三>示  
箱底放保丽龙板,再依次将指定数量的卷装产品放入箱内,四角分别放入四个三角护板,最上层再放上保丽龙板.
5. 封箱,在封好的纸箱上按客户要求写上料号,数量等



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: SIM PUSH H1.8(铁壳脚间距5.25)客户图	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	SIM-131-ARP8
DECIMALS:	ANGLES:	DWN		
.X:±0.30	X.':±2'	CHKD		
.XX:±0.20	X.X':±1"	APVD		
.XXX:±0.10		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		Website address	REV:A	